##

PTO/SB/106 (8-96)

Approved for use through 9/30/98. OMB 0651-0032 Patent and Trademark Office; U.S. DEPARTMENT OF COMMERCE

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of Information unless it displays a valid OMB control number

## **Declaration and Power of Attorney For Patent Application**

As a below named inventor, I hereby declare that:				
My residence, post office address and citizenship are as stated next to my name.				
I believe I am the original, first and sole inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled.				
LIQUID SPRAY UNIT, METHOD OF SPRAYING LIQUID USING IT,				
AND CHEMICAL				
the specification of which is attached hereto unless the following box is checked:				
was filed on 12 September 2002 as United States				
<b>A</b> Was med en				
Application Number or PCT International Application				
Application Number or PCT International Application				
Application Number or PCT International Application Number PCT/JP2002/009371 and was amended on (if				
Application Number or PCT International Application Number $\frac{\text{PCT}/\text{JP2002}/009371}{\text{policable}}$ and was amended on (if applicable).				
applicable).				
applicable).  I hereby state that I have reviewed and understand the contents of the above identified				
applicable).				
applicable).  I hereby state that I have reviewed and understand the contents of the above identified				
applicable).  I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.  I acknowledge the duty to disclose information which is material to patentability as defined				
applicable).  I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.				
applicable).  I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.  I acknowledge the duty to disclose information which is material to patentability as defined				
applicable).  I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.  I acknowledge the duty to disclose information which is material to patentability as defined				

Page 1 of 3

Burden Hour Statement: This form is estimated to take 0.4 hours to complete. Time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, Patent and Trademark Office, Washington, Declaration 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner of Patents and Trademarks, Washington, Declaration 20231.

I hereby claim foreign priority under Title 35, United States Code, Section 119 (a)-(d) or 365(b) of any foreign application(s) for patent or inventor's certificate, or 365(a) of any PCT International application which designated at least one country other than the United States, listed below and have also identified below, by checking the box, any foreign application for patent or inventor's certificate, or PCT International application having a filing date before that of the application on which priority is claimed.

Prior Foreign Application(s)			Priority Not Claimed	
2002-224234	Japan	31 July 2002		
(Number)	(Country)	(Day/Month/Year Filed)		
(Number)	(Country)	(Day/Month/Year Filed)	. 🗆	
I hereby claim the benefit under Title 35, United States Code, Section 119(e) of any United States provisional application(s) listed below.				
(Applica	ation No.)	Filing	Date	

I hereby claim the benefit under Title 35, United States Code, Section 120 of any United States application(s), or 365(c) of any PCT International application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT International application in the manner provided by the first paragraph of Title 35, United States Code Section 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, Section 1.56 which became available between the filing date of the prior application and the national or PCT International filing date of application.

PCT/JP2002/009371 12 September 2002 Pending

(Application No. ) (Filing Date) (Status: Patented, Pending, Abandoned)

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

POWER OF ATTORNEY: As a named inventor, I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith (list name and registration number)

Dale H. Thiel, Reg. No. 24 323
David G. Boutell, Reg. No. 25 072
Ronald J. Tanis, Reg. No. 22 724
Terryence F. Chapman, Reg. No. 32 549
Mark L. Maki, Reg. No. 36 589

Liane L. Churney, Reg. No. 40 694
Brian R. Tumm, Reg. No. 36 328
Steven R. Thiel, Reg. No. 53 685
Donald J. Wallace, Reg. No. 43 977
Sidney B. Williams, Jr., Reg. No. 24 949

Send Correspondence to:
FLYNN, THIEL, BOUTELL & TANIS, P.C.
2026 Rambling Road
Kalamazoo, Michigan 49008-1631

Direct Telephone Calls to: (name and telephone number)

1-00

Full name of first inventor

Hiroshi SEKIYA

Inventor's signature

Date
February 14, 2005

Residence
Tokyo, Japan

Citizenship
Japanese

Post Office Address c/o MAINTECH CO., LTD.
1-28-14, Nagasaki, Toshima-ku, Tokyo 171-0051, Japan

Page 3 of 3